



### LMDS Material Safety Data Sheet

No.	Material Content Declaration					
	Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
1	Lead wire 69.44%	Copper (Cu)	7440-50-8	55.530	99.96	694,125.0
		Phosphorus (P)	7723-14-0	0.0009	0.0017	11.8
		Arsenic (As)	7440-38-2	0.0009	0.0017	11.8
		Tin (Sn)	7440-31-5	0.0009	0.0017	11.8
		Oxygen (O)	7782-44-7	0.0005	0.0008	5.9
		Sulfur (S)	7704-34-9	0.0113	0.0203	141.0
		Iron (Fe)	7439-89-6	0.0006	0.0011	7.8
		Nickel (Ni)	7440-02-0	0.0003	0.0005	3.5
		Bismuth (Bi)	7440-69-9	0.0019	0.0034	23.5
		Antimony (Sb)	1309-64-4	0.0019	0.0034	23.5
		Lead (Pb)	7439-92-1	0.0005	0.0008	5.9
		Zinc (Zn)	7440-66-6	0.0003	0.0005	3.5
<b>Total</b>			<b>55.55</b>			
2	Solder wafer 5.49%	Lead (Pb)	7439-92-1	4.06	92.48	50,750.0
		Tin (Sn)	7440-31-5	0.22	5.01	2,750.0
		Silver (Ag)	7440-22-4	0.11	2.51	1,375.0
		<b>Total</b>			<b>4.39</b>	
3	Chip 4.5%	Silicon (Si)	7440-21-3	3.60	100.00	45,000.0
		<b>Total</b>			<b>3.60</b>	
4	Molding 20.13%	Silica (SiO <sub>2</sub> )	14808-60-7	11.76	73.00	555,246.0
		Epoxy resin	29690-82-2	2.74	17.00	129,303.9
		Phenolic resin	9003-35-4	1.42	8.80	66,933.8
		Antimony trioxide(S	1309-64-4	0.11	0.70	5,324.3
		Brominated epoxy r	40039-93-8	0.07	0.46	3,498.8
		Carbon Black	1333-86-4	0.01	0.04	304.2
<b>Total</b>			<b>16.11</b>			
5	Plating 0.44%	Tin (Sn)	7440-31-5	0.35	100.00	4,375.0
		<b>Total</b>			<b>0.35</b>	
		<b>Total mass (mg)</b>		<b>80.00</b>		